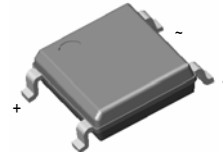




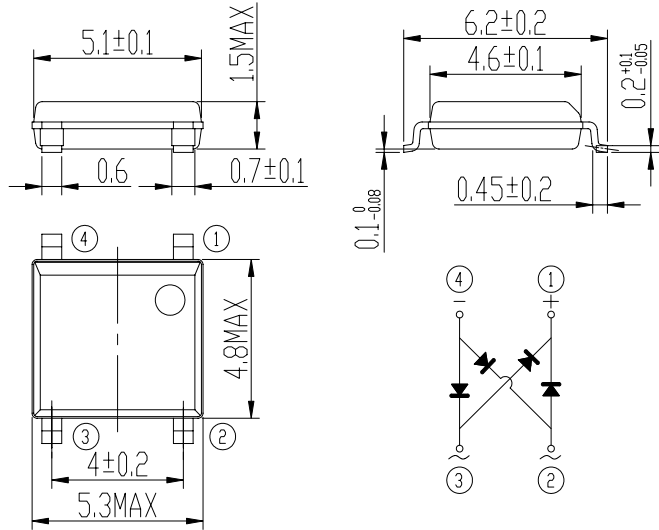
Features

- Low Profile: Typical height of 1.4mm
- Ideal for automated placement
- High surge current capability
- Solder Dip 260 , 40seconds



Mechanical Data

- Case:SOPA-4
- Epoxy meets UL-94V-0 Flammability rating
- Terminals:Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
- Polarity:As markde on body



Maximum Ratings & Electrical Characteristics Ratings at 25

ambient temperature unless otherwise specified.

Parameter	Symbol	LB2S	LB4S	LB6S	LB8S	LB10S	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	800	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average forward output rectified current on glass-epoxy P.C.B on aluminum substrate	$I_{F(AV)}$	1.0 0.8					A
Peak forward surge current 8.3 ms single sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Rating for fusig ($t < 8.3ms$)	I^2t	3					A ² sec
Maximum instantaneous forward voltage drop per diode at 0.4A	VF	0.95					V
Maximum DC reverse current at $T_A=25$ rated DC blocking voltage per leg $T_A=125$	IR	5 500					μA
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	80 25					/W
Operating junction temperature range	T_J	-55 to +150					
Storage temperature range	T_{STG}	-55 to +150					

- Notes:** 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.
2. JEDEC registered values



RATINGS AND CHARACTERISTIC CURVES

(TA=25 unless otherwise noted)

